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## Product Change Notification - JAON-20DZPV439

**Date:** 18 Oct 2016  
**Product Category:** Memory; 8-bit Microcontrollers  
**Notification subject:** CCB 2598 Final Notice:Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 8L SOIJ package at MTAI site  
**Notification text:** **PCN Status:**  
Final notification

### Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

### Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 8L SOIJ package at MTAI assembly site.

### Pre Change:

Using Gold (Au) or Palladium coated copper (PdCu) bond wire.

### Post Change:

Using Palladium coated copper with gold flash (CuPdAu) bond wire.

### Pre and Post Change Summary:

	Pre Change	Post Change
<b>Assembly Site</b>	MTAI assembly site	MTAI assembly site
<b>Wire material</b>	Au or PdCu wire	CuPdAu wire
<b>Die attach material</b>	8390A	8390A
<b>Molding compound material</b>	G600	G600
<b>Lead frame material</b>	CDA194	CDA194

### Impacts to Data Sheet:

None

### Change Impact:

None

### Reason for Change:

To improve manufacturability and qualify Palladium coated copper with gold flash (CuPdAu) bond wire.

### Change Implementation Status:

In Progress

**Estimated First Ship Date:**  
November 25, 2016 (date code: 1647)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	June 2016					->	October 2016				November 2016			
Workweek	22	23	24	25	26		40	41	42	43	44	45	46	47
Initial PCN Issue Date			X											
Qual Report Availability									X					
Final PCN Issue Date									X					
Estimated Implementation Date														X

**Method to Identify Change:**  
Traceability code

**Qualification Report:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**  
**June 13, 2016:** Issued initial notification.  
**October 18, 2016:** Issued final notification. Attached the qualification report. Provided estimated first ship date November 25, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**  
[PCN\\_JAON-20DZPV439\\_Qual Report.pdf](#)  
[PCN\\_JAON-20DZPV439\\_Affected\\_CPN.pdf](#)  
[PCN\\_JAON-20DZPV439\\_Affected\\_CPN.xls](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-20DZPV439
CATALOG_PART_NBR
24AA128-I/SM
24AA128T-I/SM
24AA256/SM
24AA256-E/SM
24AA256-I/SM
24AA256T/SM
24AA256T-E/SM
24AA256T-I/SM
24AA32A/SM
24AA32A-I/SM
24AA32AT/SM
24AA32AT-I/SM
24AA512-I/SM
24AA512-I/SMRVE
24AA512T-I/SM
24AA512T-I/SMRVE
24AA64-E/SM
24AA64-I/SM
24AA64T-E/SM
24AA64T-I/SM
24FC128-I/SM
24FC128T-I/SM
24FC256-I/SM
24FC256T-I/SM
24FC512-I/SM
24FC512T-I/SM
24FC512T-I/SMRVE
24FC64-I/SM
24FC64T-I/SM
24LC128-E/SM
24LC128-I/SM
24LC128-I/SMRVF
24LC128T-E/SM
24LC128T-I/SM
24LC128T-I/SMG
24LC256-E/SM
24LC256-I/SM
24LC256-I/SMRVE
24LC256-I/SMRVF
24LC256T-E/SM
24LC256T-E/SMRVF
24LC256T-I/SM
24LC256T-I/SMG

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Affected Catalog Part Numbers (CPN)

PCN_JAON-20DZPV439
CATALOG_PART_NBR
24LC256T-I/SMRVE
24LC256T-I/SMRVF
24LC32A/SM
24LC32A-E/SM
24LC32A-I/SM
24LC32AT/SM
24LC32AT-E/SM
24LC32AT-I/SM
24LC512-E/SM
24LC512-I/SM
24LC512-I/SMA21
24LC512-I/SMG
24LC512-I/SMRVE
24LC512T-E/SM
24LC512T-I/SM
24LC512T-I/SMRVE
24LC64-E/SM
24LC64-I/SM
24LC64-I/SMRVE
24LC64T-E/SM
24LC64T-I/SM
24LC64T-I/SMRVE
25AA1024-I/SM
25AA1024-I/SMB21
25AA1024T-I/SM
25AA1024T-I/SMB21
25AA128-I/SM
25AA128T-I/SM
25AA256-E/SM
25AA256-I/SM
25AA256T-E/SM
25AA256T-I/SM
25AA512-I/SM
25AA512T-I/SM
25LC1024-E/SM
25LC1024-I/SM
25LC1024-I/SMA21
25LC1024-I/SMA23
25LC1024T-E/SM
25LC1024T-I/SM
25LC1024T-I/SMA23
25LC128-E/SM
25LC128-I/SM

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Affected Catalog Part Numbers (CPN)

PCN_JAON-20DZPV439
CATALOG_PART_NBR
25LC128T-E/SM
25LC128T-I/SM
25LC256-E/SM
25LC256-I/SM
25LC256T-E/SM
25LC256T-I/SM
25LC512-E/SM
25LC512-I/SM
25LC512T-E/SM
25LC512T-I/SM
PIC12F509-E/SM
PIC12F509-I/SM
PIC12F509T-E/SM
PIC12F509T-I/SM
PIC12F509T-I/SM034
PIC12F509T-I/SM035
PIC12F509T-I/SM036
PIC12F509T-I/SM037
PIC12F509T-I/SM038